

IN THE CLAIMS:

Please cancel claims 1-8 without prejudice to or disclaimer of the subject matter recited therein.

Please add new claims 9-16 as follows:

LISTING OF CURRENT CLAIMS

Claims 1-8. (Canceled)

Claim 9. (New) A sink compound laminate molding process, which comprises the steps of:

- a) preparing a sheet copper material having a thickness between 0.1mm and 8.0 mm;
- 5 b) placing the copper sheet material in a molding cavity and positioning a bottom of the copper sheet material against a bottom of the molding cavity;
- c) heating the copper sheet material to a temperature between 360°C and 650°C and performing one of injecting an inert gas into the
10 molding cavity and maintaining a vacuum in the molding cavity to prevent oxidization from taking place on the surface of the copper material;
- d) pouring a molten aluminum material over the sheet copper material in the molding cavity using a gravity casting process to create a diffusion
15 bonding to an interface between both of the copper and aluminum materials; and
- e) cooling and curing the aluminum material forming a structure of a compound laminate of an integrated heterogeneous alloy of copper and aluminum, wherein crystals are present in the interface between
20 the copper and the aluminum materials.

Claim 10. (New) A sink compound laminate molding process as claimed in claim 9, wherein in the heating step c), the inert gas is introduced into the molding cavity in the course of heating the copper material to prevent oxidization from taking place on the surface of the copper material .

Claim 11. (New) A sink compound laminate molding process as claimed in claim 9, wherein in the heat step c), the vacuum is maintained in the molding cavity during the course of heating the copper material to prevent oxidization from taking place on the surface of the copper material.

Claim 12. (New) A sink compound laminate molding process as claimed in claim 9, wherein the copper sheet material is pure copper.

Claim 13. (New) A sink compound laminate molding process as claimed in claim 9, wherein the copper sheet material is a copper alloy.

Claim 14. (New) A sink compound laminate molding process as claimed in claim 9, wherein the sheet copper material is a shape selected from the group consisting of a triangle and a strip.

Claim 15. (New) A sink compound laminate molding process as claimed in claim 9, wherein the aluminum material is pure aluminum.

Claim 16. (New) A sink compound laminate molding process as claimed in claim 9, wherein the aluminum material is an aluminum alloy selected from the group consisting of AlSiCu, AlSiZn, AlSiMg, AlSiCuMg, AlGe, AlGeSi, AlCu, AlMn, AlMg, AlLi, AlSn and AlPb.